

Title (en)

METHOD FOR MANUFACTURING A SEMICONDUCTOR DEVICE AND SUPPORT PLATE THEREFOR

Title (de)

HERSTELLUNGSVERFAHREN FÜR HALBLEITERVORRICHTUNG UND TRÄGER DAFÜR

Title (fr)

PROCEDE DE PRODUCTION D'UN DISPOSITIF A SEMI-CONDUCTEUR, DISPOSITIF A SEMI-CONDUCTEUR AINSI OBTENU ET PLAQUE DE SUPPORT ADAPTEE POUR CE DISPOSITIF A SEMI-CONDUCTEUR

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Abstract (en)

[origin: WO02089184A2] The invention relates to a method of manufacturing a semiconductor device (10) comprising a semiconductor element (1), with two or more elements (1) being attached to a support plate (2). It is often desired in such a case that the elements(1) are positioned on the support plate (2) or on a further support plate (22) at a larger mutual distance than in the semiconductor body (100) in which the elements (1) are formed. According to the invention, the support plate (2) is formed as an array of rigid subplates (2A) to which the elements (1) are attached, and the rigid subplates (2A) are interconnected within the plate (2) by means of one or more flexible elements (3). In this way the elements (1) - after they have been attached to the support plate (2) and after they have been separated from each other within the semiconductor body (100) and after stretching of the flexible elements (3) - can be positioned in an accurate manner at a larger mutual distance. Subsequently - or after having been transferred to a further plate (22) - the elements (1) may be provided with an encapsulation (20) and can be mounted on to individual semiconductor devices (10).

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